

IN THE SPECIFICATION:

(1) Kindly replace original paragraph [0030] with the following rewritten paragraph:

--[0030] Level 6 conductive vias 142, formed in a dielectric layer 144, are in electrical contact with the underlying level 5 conductive runners 132 and 134. A dielectric barrier layer 145, serving the same purpose as the dielectric barrier layer 140, overlies the dielectric layer 144. A power bus 146 is formed in an oxide layer 148 overlying the dielectric layer 144. According to the dual damascene process described above, the conductive vias 142 and the power bus 146 are formed simultaneously in previously formed via openings and trenches. Note the larger cross-sectional area required for the power bus 146 compared with the ~~level 6~~level 5 conductive runners 132 and 134. This is preferred as the power bus 146 carries higher currents than the low-current signals carried by the conductive runners 132 and 134.--